

Towards a 200G/lane Backplane Objective

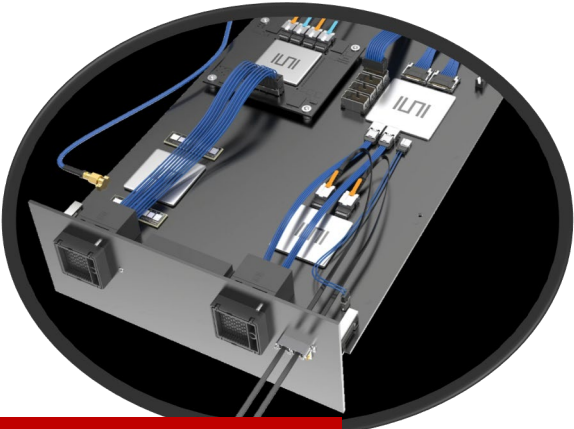
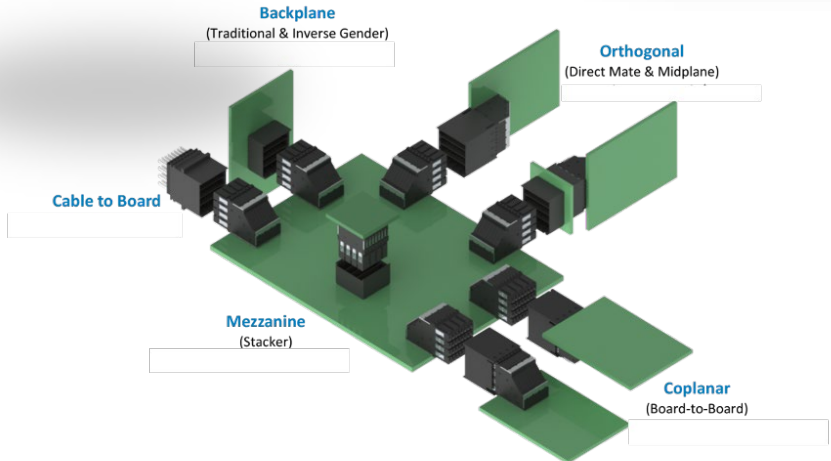
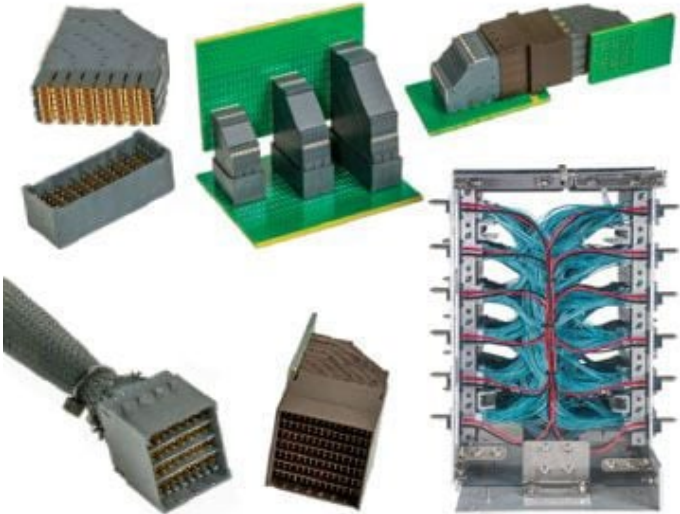
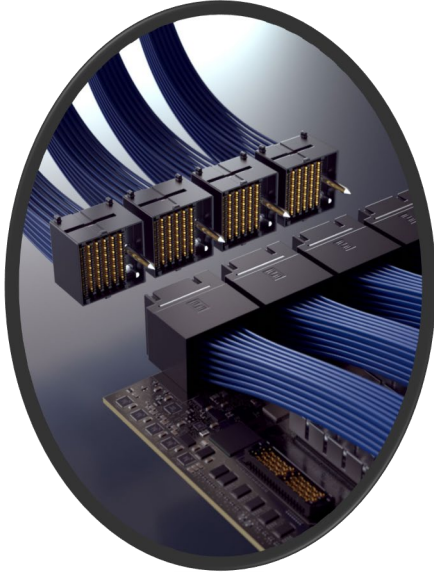
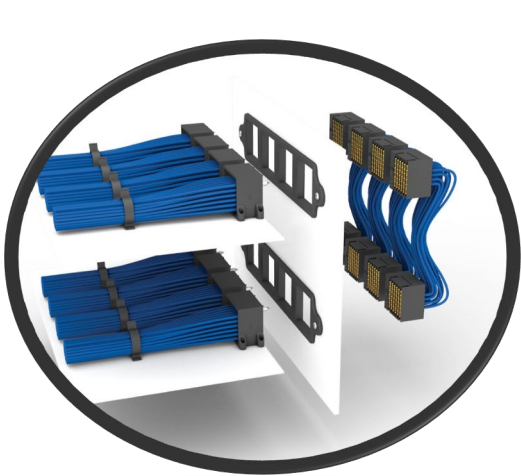
Kent Lusted, Intel
Howard Heck, Intel
Rich Mellitz, Samtec
Tom Palkert, Samtec
Jim Weaver, Arista
Jason Chan, Arista
Nathan Tracy, TE
Megha Shanbag, TE
Sam Kocsis, Amphenol
Priyank Shukla, Synopsys

January 4, 2023

What we know today versus one year ago?

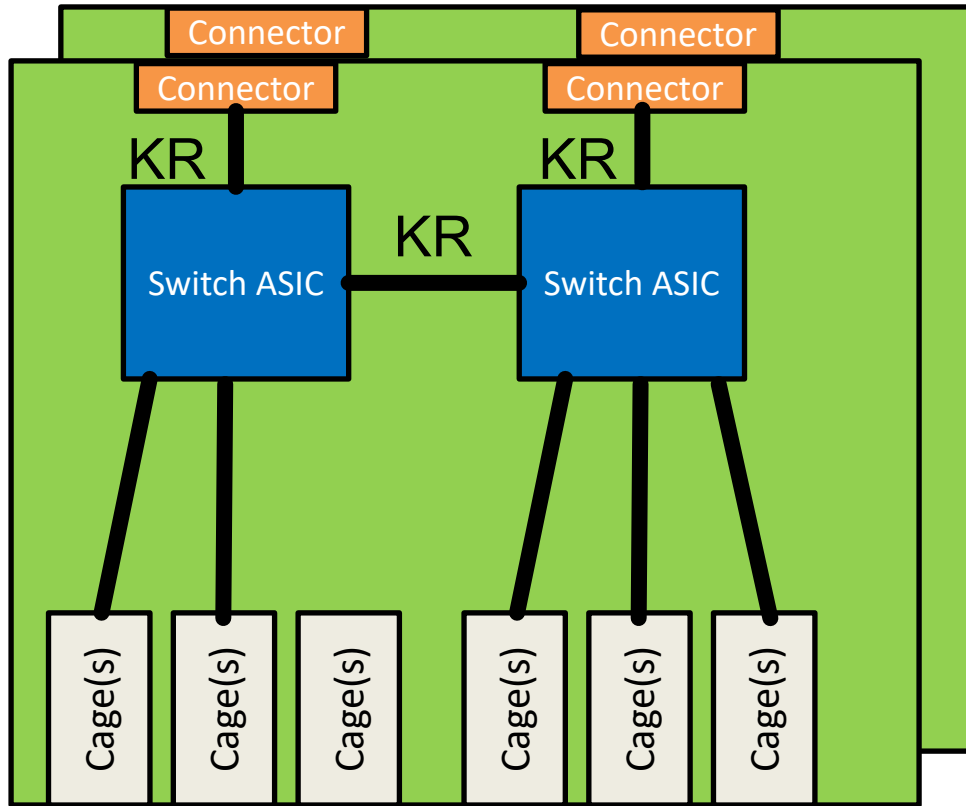
- Original P802.3df TF split to two Task Forces
 - Welcome [P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force!](#)
- PAM-4 Modulation selected for 200 Gbps/lane Optics (500m and 2km), and 200 Gbps/lane AUIs. Expect reaffirmation by 3dj
 - See https://www.ieee802.org/3/df/KeyMotions_3df_221117.pdf
 - Nyquist frequency = 53.125GHz
- Backplane PHYs still being broadly used Ethernet deployments today
 - Individuals have submitted backplane-like channels for consideration by the TF (see: <https://www.ieee802.org/3/df/public/tools/index.html>)

Backplane Interconnects of Today and Tomorrow

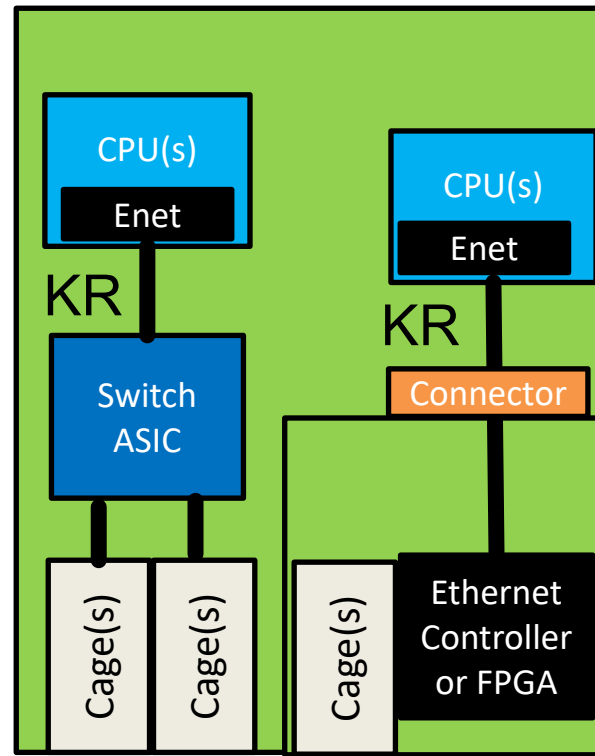


Backplane Ethernet is more than a “traditional” PCB backplane

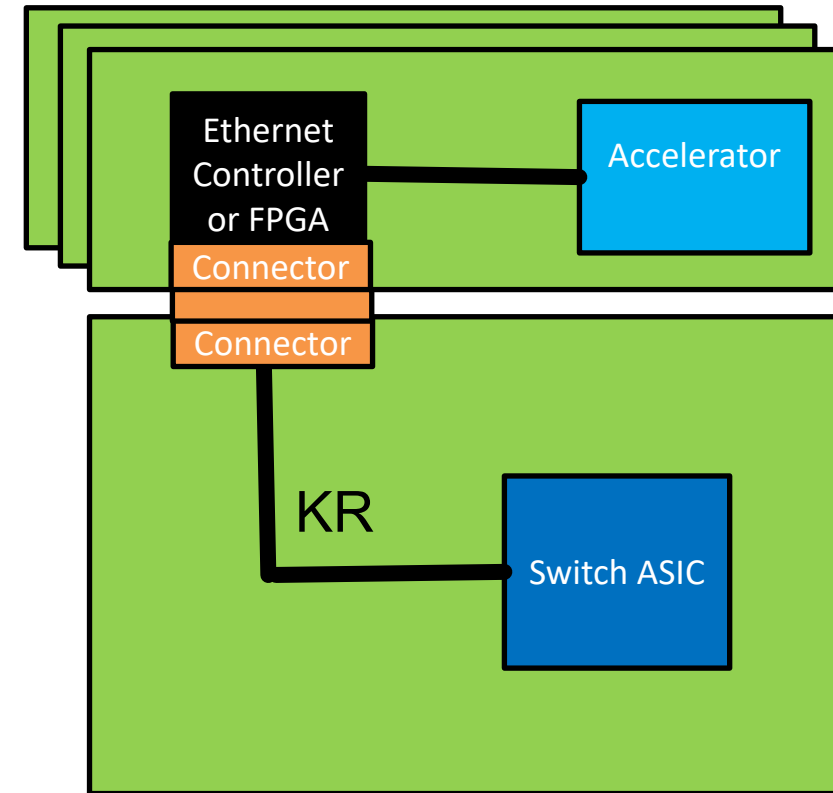
Some Examples of How Backplane PHYs are Used



Switches (inter line-card)



Telcom System



Blade System

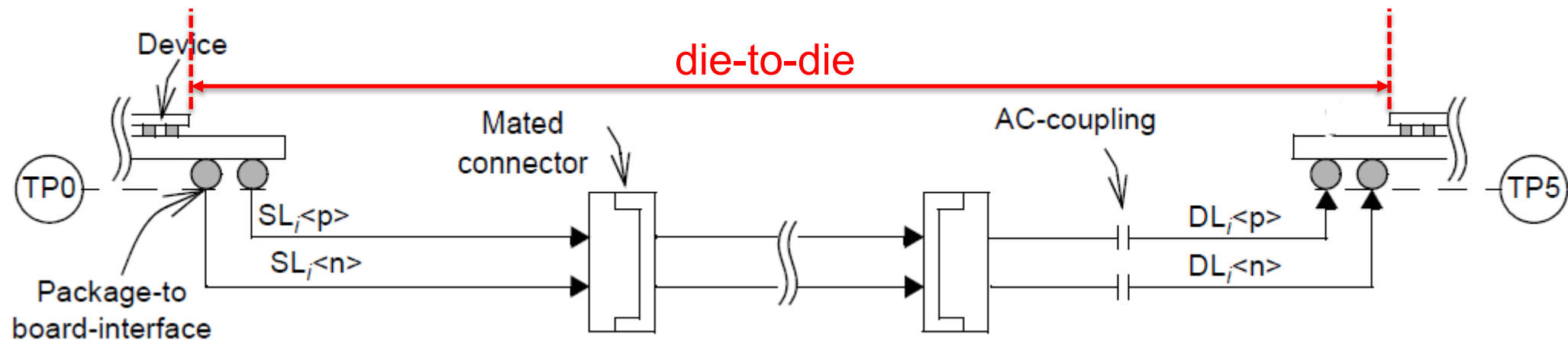
Backplane Ethernet rates need to scale to support user needs

Revisiting the Backplane Objective Format

- For the last ~10 years (3bj, 3by, 3cd, 3ck, 3df), backplane objectives were implied as “ball to ball” (TP0-TP5)
 - Example from P802.3df: “Define a physical layer specification that supports 800 Gb/s operation over eight lanes over electrical backplanes supporting an insertion loss ≤ 28 dB at 26.56GHz”
 - https://www.ieee802.org/3/df/proj_doc/objectives_P802d3df_221117.pdf
- However, the backplane channels includes fixed packages at both ends
- At 200 Gbps/lane, we may find a broader application space by using a more holistic definition of the backplane channel including the packages

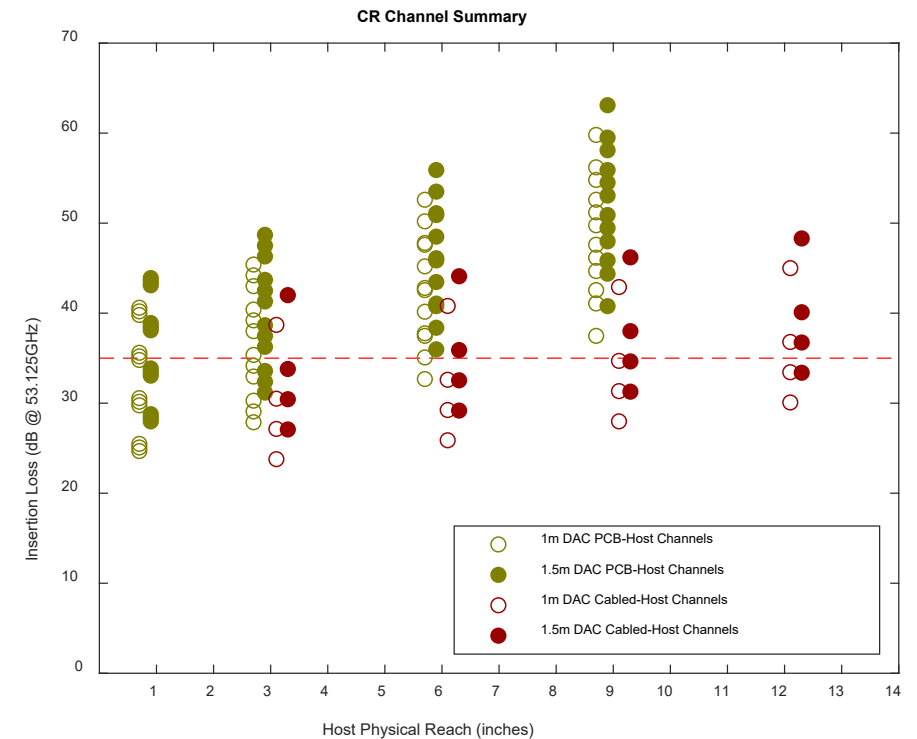
Proposed Backplane Objective Format

- Reshape the backplane objective format to be inclusive of the package structures → die-to-die
 - Test points and compliance methods would be a subject for baseline proposals
- Example: “Define a physical layer specification that supports $[n \times 200]$ Gb/s operation over $[n]$ lanes over electrical backplanes supporting an insertion loss $\leq X$ dB (die-die) at 53.125 GHz”



Potential Path to Enable Passive Copper Cables

- Backplane can set the channel die-to-die loss guardrails for all passive interconnect
- An objective specifying die-to-die loss would significantly help the analysis of passive copper cable, which has been an open request by the TF



https://www.ieee802.org/3/B400G/public/21_08/kocsis_b400g_01a_210826.pdf

Proposed Straw Poll #1

- I am interested in backplane PHY objectives for 200Gbps/lane rates
- Y, N, A

Proposed Straw Poll #2

- I would support adopting a set of 200 Gbps/lane backplane objectives of the form:
 - “Define a physical layer specification that supports $[n*200]$ Gb/s operation over $[n]$ lanes over electrical backplanes supporting an insertion loss $\leq X$ dB (die-die) at 53.125 GHz”
- Y, N, A

THANKS!

Objectives as documented in P802.3ck

- Define a [n-lane, 100G/lane] PHY for operation over twin-axial copper cables with lengths up to at least 2 meters
- Define a [n-lane, 100G/lane] PHY for operation over electrical backplanes supporting an insertion loss $\leq 28\text{dB}$ at 26.56GHz